

Title (en)

PLANT AND METHOD FOR HOT FORMING BLANKS

Title (de)

ANLAGE UND VERFAHREN ZUM WARMUMFORMEN VON PLATINEN

Title (fr)

INSTALLATION ET PROCÉDÉ DE DÉFORMATION À CHAUD DE PLATINES

Publication

EP 2806041 A2 20141126 (DE)

Application

EP 14001687 A 20140513

Priority

DE 102013008853 A 20130523

Abstract (en)

[origin: CA2851920A1] The present invention pertains to a system for hot-forming blanks (P) with at least one heating device (4) and at least one pressing device (2) that is arranged downstream of the at least one heating device (4), wherein at least one reheating device (6) for at least partially acting upon the blanks (P) formed in the pressing device with heat is provided downstream of the pressing device (2).

Abstract (de)

Die vorliegende Erfindung betrifft eine Anlage zum Warmumformen von Platinen (P) mit wenigstens einer Erwärmungseinrichtung (4) und wenigstens einer stromabwärtig der wenigstens einen Erwärmungseinrichtung (4) angeordneten Presseeinrichtung (2), wobei stromabwärtig der Presseeinrichtung (2) wenigstens eine Nacherwärmungseinrichtung (6) zur wenigstens partiellen Wärmebeaufschlagung der in der Presseeinrichtung umgeformten Platinen vorgesehen ist.

IPC 8 full level

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CPC (source: EP US)

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Citation (applicant)

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Cited by

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DOCDB simple family (publication)

EP 2806041 A2 20141126; **EP 2806041 A3 20150415**; BR 102014012331 A2 20150120; CA 2851920 A1 20141123; CN 104174795 A 20141203; DE 102013008853 A1 20141127; IN 2508CH2014 A 20150703; KR 20140138074 A 20141203; TW 201504444 A 20150201; TW I589702 B 20170701; US 2014345753 A1 20141127

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